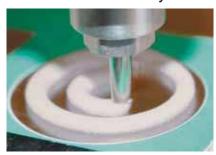
Gap Filler 1000 (Two-Part)

Thermally Conductive, Liquid Gap Filling Material

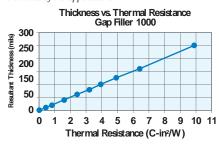
Features and Benefits

- Thermal conductivity: 1.0 W/m-K
- Ultra-conforming designed for fragile and low-stress applications
- · Ambient and accelerated cure schedules
- 100% solids no cure by-products
- Excellent low and high temperature mechanical and chemical stability



Gap Filler 1000 is a thermally conductive, liquid cap filling material. It is supplied as a twocomponent, room or elevated temperature curing system. The material is formulated to provide a balance of cured material properties highlighted by a low modulus and good compression set (memory). The result is a soft, thermally conductive, form-in-place elastomer ideal for coupling "hot" electronic components mounted on PC boards with an adjacent metal case or heat sink Before cure, Gap Filler 1000 flows under pressure like a grease. After cure, it does not pump from the interface as a result of thermal cycling Unlike thermal grease, the cured product is dry to the touch. Unlike cured gap filling materials, the liquid approach offers infinite thickness with little or no stress during displacement and eliminates the need for specific pad thickness and die-cut shapes for individual applications Gap Filler 1000 is intended for use in thermal interface applications when a strong structural bond is not required.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP FILLER 1000 PRO PERTY IMPERIAL VALUE METRIC VALUE TEST METHOD Color / Part A Gray Gray Visual Visual Color / Part B W hite W hite **ASTM D2196** Viscosity as Mixed (cps) (1) 100.000 100.000 Density (g/cc) 1.6 1.6 ASTM D792 Mix Ratio 1:1 1:1 Shelf Life @ 25℃ (months) 6 6 PROPERTY AS CURED Gray Grav Vig pl Hardness (Shore 00) (2) 30 30 **ASTM D2240** Heat Capacity (Jg-K) 1.0 1.0 **ASTM E1269** -76 to 347 -60 to 175 Continuous Use Temp (°F) / (°C) **ELECTRICAL AS CURED** 500 500 ASTM D149 Dielectric Strength (V/mil) Dielectric Constant (1000 Hz) 5.0 ASTM D150 5.0 Volume Resistivity (Ohm-meter) 10¹¹ 10¹¹ ASTM D257 V-O V-O **U.L. 94** THERMAL AS CURED Thermal Conductivity (W/m-K) 1.0 1.0 **ASTM D5470** CURE SCHEDULE Pot Life @ 25℃ (min) (3) 15 15 Cure @ 25℃ (min) (4) 60 - 120 60 - 120 Cure @ 100°C (min) (4) 5

- 1) Brookfield RV, Heli-Path, Spindle TF @ 20 rpm, 25°C.
- 2) Thirty second delay value Shore 00 hardness scale.
- Time for viscosity to double.
- Cure schedule (rheometer time to read 90% cure)

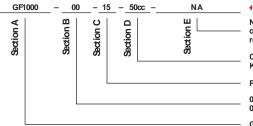
Typical Applications Include:

- Automotive electronics
- Telecommunications
- · Computer and peripherals
- Thermally conductive vibration dampening
- · Between any heat-generating semiconductor and a heat sink

Configurations Available:

· Supplied in cartridge and kit form

Building a Part Number



Standard Options

≪ examble

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Cartridges: 50cc = 50.0cc, 400cc = 400.0cc Kits: 1200cc = 1200.0cc, or 10G = 10 gallon

Pot Life: 15 = 15 minutes

00 = No spacer beads 07 = 0.007" spacer beads

GF1000 = Gap Filler 1000 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others

BERUQUIST

www.bergquistcompany.com

The Bergquist Company -North American Headquarters 18930 West 78th Street Chanhassen, MN 55317 Phone: 800-347-4572 Fax: 952-835-0430 The Bergquist Company -European Headquarters Bramenberg 9a, 3755 BT Eemnes Netherlands Phone: 31-35-5380684 Fax: 31-35-5380295 The Bergquist Company - Asia Room 15, 8/FWah Wai Industrial Centre No. 38-40, Au Pui Wan Street Fotan, Statin, N.T. Hong Kong Ph. 852.2690.9296 Fax: 852.2690.2344 All statements, technical information and recommendations herein are based on tests we believe to be reliable, and THE FOLLOWING IS MADE IN LIBU OF ALL WARRANTIES, EXPRESSED OR MIRHED, INCLUDING THE IMPLID WARRANTIES FOR PURPOSE. Sellers' and manufacturers only obligation shall be to replace such quantity of the product proved to be defective. Before using user shall determine the suitability of the product for its intended use, and the user assumes all risks and liability whistoever in connection therewith. NETHER SELLER NOR MANUFACTURER SHALL BE LIABLE EITHER IN TORT OR IN CONTRACT FOR ANY LOSS OR DAMAGE, DIRECT, INCIDENTAL, OR CONSEQUENTIAL, INCLUDING LOSS OF PROFITS OR REVENUE ARISING OUT OF THE USE OR THE INABILITY TO USE A PRODUCT, No statement, purchase order or recommendations by seller or purchaser not contained herein shall have any force or effect unless in an agreement signed by the officers of the seller and manufacturer.